## TOSHIBA PHOTO-IC Si MONOLITHIC PHOTO-IC

# **TPS830**

HIGH-SPEED OPTICAL REMOTE CONTROLLERS
CORDLESS CONTROLLERS FOR VIDEOGAMES
ELECTRONIC ORGANIZERS AND OTHER NEW
PORTABLE INFORMATION DEVICES

IR DATA COMMUNICATIONS

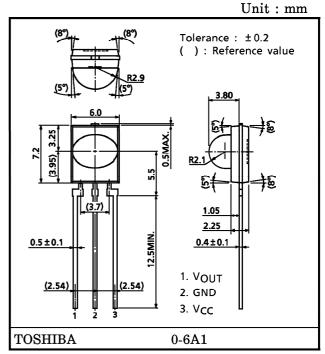
 Photodiode, I-V converter, band-pass filter and AGC amplifier all incorporated in a single chip

• Carrier frequency :  $f_0 = 455 \text{ kHz (typ.)}$ 

• Supply voltage : V<sub>CC</sub> = 5 V

• Visible light cut-off frequency :  $\lambda > 700 \text{ nm}$ 

 TLN105B and TLN231 available as infrared LEDs for remote controllers



Weight: 0.3 g (typ.)

## MAXIMUM RATINGS (Ta = 25°C)

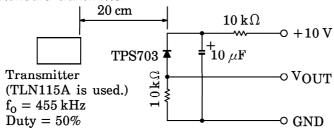
CHARACTERISTIC	SYMBOL	RATING	UNIT	
Supply Voltage	$v_{CC}$	7	V	
Output Current	IO	±10	$\mu$ <b>A</b>	
Operating Temperature Range	${ m T_{opr}}$	-20~60	$^{\circ}\mathrm{C}$	
Storage Temperature Range	$\mathrm{T_{stg}}$	-30~100	$^{\circ}\mathrm{C}$	
Soldering Temperature Range (5 s)	$T_{sol}$	260	$^{\circ}\mathrm{C}$	

CHARACTERISTIC	SYMBOL	TEST CONDITION	Min	Тур.	Max	UNIT
Supply Voltage	$v_{\rm CC}$	_	3	5	7	V
Supply Current	$I_{CC}$	E = 0	_	1.2	3.0	mA
Electromagnetic Sensitivity	ES	(Note 5)	_	250	_	$V_{p-p}/m$
Transmission Range	L (Note 3)	The burst wave shown in Note		6	_	m
High-Level Output Voltage	$v_{OH}$	4 is transmitted by a standard		_		V
Low-Level Output Voltage	$v_{ m OL}$	transmitter (Note 2).		_	0.5	V
ON Pulse Width	$T_{ON}$	External light intensity < 500 ℓx	16	25	40	μs
OFF Pulse Width	$T_{ m OFF}$	Output current $< 10~\mu A$	1	63	-	$\mu$ s
Carrier Frequency	$f_0$	_		455		kHz
Peak Sensitivity Wavelength	$\lambda \mathbf{P}$	_		900		nm
Radiation Angle	$\theta_{\mathbf{H}}$	Horizontal angle, L/2 (Note 6)	±55	±63		0
Tradiation Angle	$\theta_{\mathbf{V}}$	Vertical angle, L/2 (Note 6)	$\pm 25$	±30		0

OPTICAL AND ELECTRICAL CHARACTERISTICS ( $V_{CC} = 5 \text{ V}$ , Ta = 25°C, C = 1000 pF : Note 1)

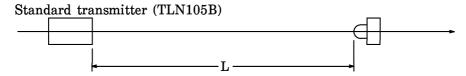
(Note 1): Measurements for the TPS830 are based on a standard circuit which includes a 1000-pF capacitor between  $V_{\rm O}$  and GND to prevent oscillation.

(Note 2): Standard transmitter



In the figure above, the transmitter output VOUT is 80 mVpp. The TPS703 in this application has a short-circuit current of  $I_{sc}=1.24~\mu A$  when measured at  $E=0.1~mW/cm^2$ . (E is the radiant incidence when a CIE standard light source A is used.)

(Note 3): Transmission range L



L is the maximum distance at which burst waves can be received from the transmitter unit, and at which data can be processed by the receiver unit.

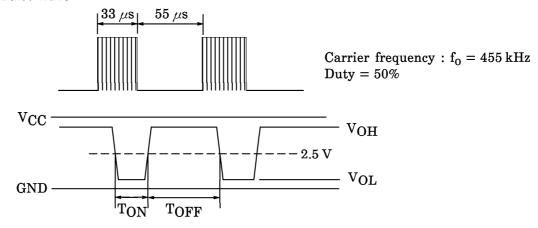
Note that when signals other than the recommended burst wave are transmitted, the transmission range may be reduced or a malfunction may occur.

(\*) The TLN105B is used as the standard LED transmitter.

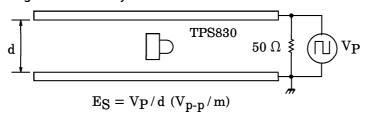
If the TLN231 is used instead, the transmission range is 1.2 times that of the TLN105B.

Example:  $6 \text{ m (with TLN105B)} \Rightarrow 10.1 \text{ m (with TLN231)}$ 

## (Note 4): Burst wave



(Note 5): Electromagnetic sensitivity

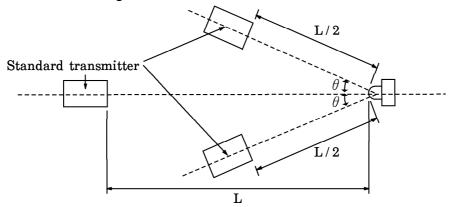


Mount the device between two parallel boards separated by a distance of d. Apply voltages modulated using frequencies ranging from  $10\,\mathrm{kHz}$  to  $50\,\mathrm{MHz}$  across the boards and read off the voltage at which noise is generated in the output from the device.

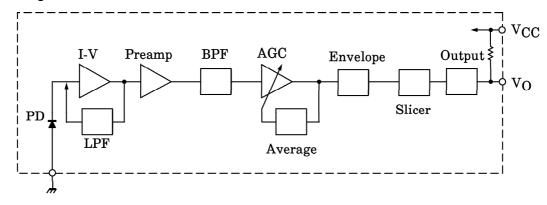
(\*) Usage in strong electromagnetic fields may affect the device.

Please evaluate product in this type of environment before releasing them for actual use.

(Note 6): Radiation angle



## Circuit Block Diagram



Bit pattern designing example (reference)

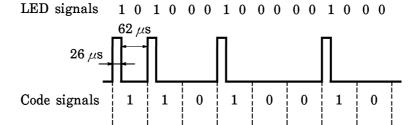
• Example of code signal = 11010010

Sequence of LED signals = 1 must be avoided. If LED signals of 1 sequence, TPS830 may not receive LED signals properly. After an LED signal of 1, 0 must be sent (55  $\mu$  or longer interval necessary). Please take this into account when designing a bit pattern.

The following shows the bit pattern t example that is converted at first code signals to LED signals as shown on the right diagram.

<conversion example=""></conversion>				
Code signal		LED signal		
0	$\rightarrow$	00		
1	$\rightarrow$	10		

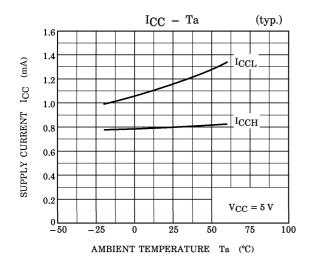
## <Pattern example>

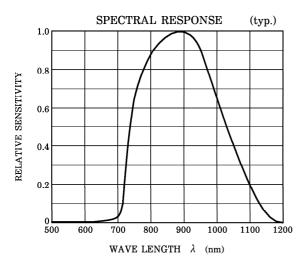


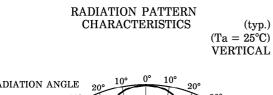
## **PRECAUTIONS**

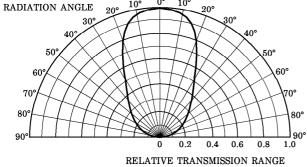
- 1. To stabilize the power line, insert a bypass capacitor of up to  $0.01\,\mu\text{F}$  between V<sub>CC</sub> and GND, close to the device.
- 2. At power-on the internal circuit takes about 100  $\mu$ s to stabilize. During this period the output signal is unstable and may change.
- 3. To avoid unnecessary oscillation, insert a bypass capacitor of 1000 pF between V<sub>CC</sub> and GND.
- 4. When using the device, please take the device's characteristics, the operating environment and the characteristics of pairing LED device into considerations.
- 5. Soldering temperature :  $\leq$  260°C, Soldering time :  $\leq$  5 s (Soldering must be performed under the 2 mm from the body of the device.)
- 6. When forming the leads, bend each lead under the 2 mm from the body of the device. Soldering must be performed after the leads have been formed.

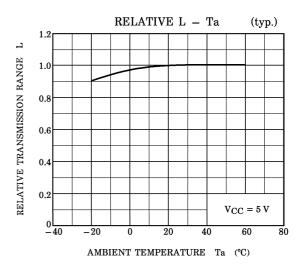
4



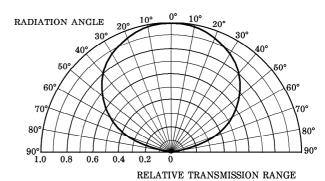


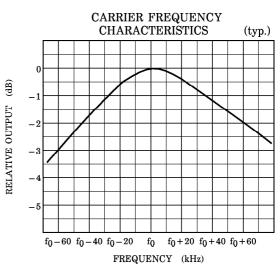












#### RESTRICTIONS ON PRODUCT USE

000707EBA

- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc..
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk.
- The products described in this document are subject to the foreign exchange and foreign trade laws.
- ◆ The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA CORPORATION for any infringements of intellectual property or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any intellectual property or other rights of TOSHIBA CORPORATION or others.
- The information contained herein is subject to change without notice.